#### Order Number: MC100ES8111/D Rev 0, 06/2002

## Preliminary Information

# Low Voltage 1:10 Differential HSTL Clock Fanout Buffer

The Motorola MC100ES8111 is a bipolar monolithic differential clock fanout buffer. Designed for most demanding clock distribution systems, the MC100ES8111 supports various applications that require the distribution of precisely aligned differential clock signals. Using SiGe technology and a fully differential architecture, the device offers very low skew outputs and superior digital signal characteristics. Target applications for this clock driver are high performance clock distribution in computing, networking and telecommunication systems.

#### Features:

- 1:10 differential clock fanout buffer
- 50 ps maximum device skew<sup>1</sup>
- SiGe technology
- Supports DC to 400 MHz operation 1 of clock or data signals
- 1.5V HSTL compatible differential clock outputs
- PECL and HSTL compatible differential clock inputs
- 3.3V power supply for device core, 1.5V or 1.8V HSTL output supply
- · Supports industrial temperature range
- Standard 32 lead LQFP package

#### **Functional Description**

The MC100ES8111 is designed for low skew clock distribution systems and supports clock frequencies up to 400 MHz<sup>1</sup>. The device accepts two clock sources. The CLK0 input accepts HSTL compatible signals and CLK1 accepts PECL compatible signals. The selected input signal is distributed to 10 identical, differential HSTL compatible outputs.

In order to meet the tight skew specification of the device, both outputs of a differential output pair should be terminated, even if only one output is used. In the case where not all 10 outputs are used, the output pairs on the same package side as the parts being used on that side should be terminated.

The HSTL compatible output levels are generated with an open emitter architecture. This minimizes part—to—part and output—to—output skew. The open-emitter outputs require a  $50\Omega$  DC termination to GND (0V). The output supply voltage can be either 1.5V or 1.8V, the core voltage supply is 3.3V. The output enable control is synchronized internally preventing output runt pulse generation. Outputs are only disabled or enabled when the outputs are already in logic low state (true outputs logic low, inverted outputs logic high). The internal synchronizer eliminates the setup and hold time requirements for the external clock enable signal. The device is packaged in a 7x7 mm² 32-lead LQFP package.

### MC100ES8111

LOW-VOLTAGE 1:10 DIFFERENTIAL HSTL CLOCK FANOUT DRIVER



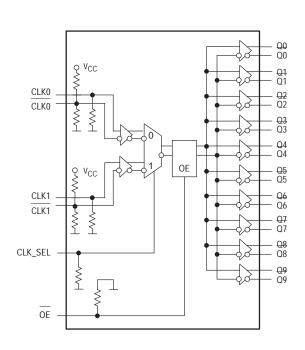
**FA SUFFIX** 32–LEAD LQFP PACKAGE CASE 873A

This document contains information on a product under development. Motorola reserves the right to change or discontinue this product without notice.

1. AC specifications are design targets and subject to change







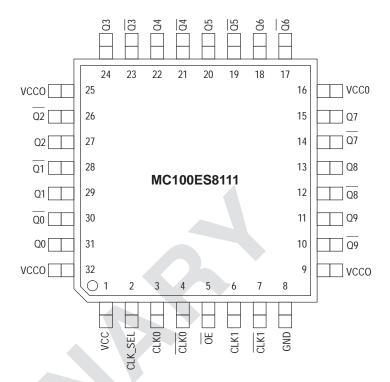


Figure 1. MC100ES8111 Logic Diagram

Figure 2. 32-Lead Package Pinout (Top View)

**Table 1. PIN CONFIGURATION** 

Pin	I/O	Туре	Function			
CLK0, CLK0	Input	HSTL	Differential HSTL reference clock signal input			
CLK1, CLK1	Input	PECL	Differential PECL reference clock signal input			
CLK_SEL	Input	LVCMOS	Reference clock input select			
OE	Input	LVCMOS	Output enable/disable. OE is synchronous to the input reference clock which eliminates possible output runt pulses when the OE state is changed.			
Q[0-9], Q[0-9]	Output	ECL/PECL	Differential clock outputs			
GND	Supply		Negative power supply			
Vcc	Supply		Positive power supply of the device core (3.3V)			
VCCO	Supply		Positive power supply of the HSTL outputs. All V <sub>CCO</sub> pins must be connected to the postive power supply (1.5V or 1.8V) for correct DC and AC operation.			

**Table 2. FUNCTION TABLE** 

Control	Default	0	1
CLK_SEL	0	CLK0, CLK0 (HSTL) is the active differential clock input	CLK1, CLK1 (PECL) is the active differential clock input
OE	0	Q[0-9], Q[0-9] are active. Deassertion of OE can be asynchronous to the reference clock without generation of output runt pulses.	Q[0-9] = L, Q[0-9] =H (outputs disabled). Assertion of OE can be asynchronous to the reference clock without generation of output runt pulses.

Table 3. Absolute Maximum Ratingsa

Symbol	Characteristics	Min	Max	Unit	Condition
VCC	Supply Voltage	-0.3	3.6	V	
Vcco	Supply Voltage	-0.3	3.1	V	
VIN	DC Input Voltage	-0.3	V <sub>CC</sub> + 0.3	V	
VOUT	DC Output Voltage	-0.3	V <sub>CC</sub> + 0.3	V	
IIN	DC Input Current		±20	mA	
lout	DC Output Current		±50	mA	
TS	Storage temperature	-65	125	°C	
T <sub>Func</sub>	Functional temperature range	T <sub>A</sub> = -40	T <sub>J</sub> = +110	°C	

a. Absolute maximum continuous ratings are those maximum values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation at absolute-maximum-rated conditions is not implied.

**Table 4. General Specifications** 

Symbol	Characteristics	Min	Тур	Max	Unit	Condition
VTT	Output termination voltage		0		V	
MM	ESD Protection (Machine model)	200			V	
HBM	ESD Protection (Human body model)	2000			V	
CDM	ESD Protection (Charged device model)	TBD			V	
LU	Latch-up immunity	200			mA	
C <sub>IN</sub>	Input Capacitance		4.0		pF	Inputs
θЈΑ	Thermal resistance junction to ambient JESD 51-3, single layer test board  JESD 51-6, 2S2P multilayer test board		83.1 73.3 68.9 63.8 57.4 59.0 54.4 52.5 50.4 47.8	86.0 75.4 70.9 65.3 59.6 60.6 55.7 53.8 51.5 48.8	°C/W °C/W °C/W °C/W °C/W °C/W °C/W °C/W	Natural convection 100 ft/min 200 ft/min 400 ft/min 800 ft/min Natural convection 100 ft/min 200 ft/min 400 ft/min 800 ft/min
θЈС	Thermal resistance junction to case		23.0	26.3	°C/W	MIL-SPEC 883E Method 1012.1
TJ	Operating junction temperature <sup>a</sup> (continuous operation) MTBF = 9.1 years			110	°C	

a. Operating junction temperature impacts device life time. Maximum continues operating junction temperature should be selected according to the application life time requirements (See application note AN1545 and the application section in this datasheet for more information). The device AC and DC parameters are specified up to 110°C junction temperature allowing the MC100ES8111 to be used in applications requiring industrial temperature range. It is recommended that users of the MC100ES8111 employ thermal modeling analysis to assist in applying the junction temperature specifications to their particular application.

Table 5. DC Characteristics ( $V_{CC} = 3.3V \pm 5\%$ ,  $V_{CCO} = 1.5V \pm 0.1V$  or  $V_{CCO} = 1.8V \pm 0.1V$ ,  $T_J = 0$ °C to + 110°C)<sup>a</sup>

Symbol	Characteristics	Min	Тур	Max	Unit	Condition
Clock inp	ut pair CLK0, CLK0 (HSTL differential signals	)		•		
V <sub>DIF</sub>	Differential input voltage <sup>b</sup>	0.2			V	
V <sub>X, IN</sub>	Differential cross point voltage <sup>C</sup>	0.25	0.68 - 0.9	V <sub>CC</sub> -1.3	V	
VIH	Input high voltage	Vx+0.1			V	
VIL	Input low voltage			V <sub>X</sub> -0.1	V	
I <sub>IN</sub>	Input Current			±150	mA	$V_{IN} = V_X \pm 0.1V$
Clock inp	ut pair CLK1, CLK1 (PECL differential signals	s)				
V <sub>PP</sub>	Differential input voltage <sup>d</sup>	0.15		1.0	V	Differential operation
VCMR	Differential cross point voltage <sup>e</sup>	1.0		V <sub>CC</sub> -0.6	V	Differential operation
VIH	Input voltage high	V <sub>CC</sub> -1.165		V <sub>CC</sub> -0.880	V	
VIL	Input voltage low	V <sub>CC</sub> -1.810		V <sub>CC</sub> -1.475	V	
I <sub>IN</sub>	Input Current <sup>a</sup>			±150	mA	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IN</sub>
LVCMOS	control inputs OE, CLK_SEL					
VIL	Input voltage low			0.8	V	
VIH	Input voltage high	2.0			V	
I <sub>IN</sub>	Input Current			±150	mA	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IN</sub>
HSTL clo	ck outputs (Q[0-9], Q[0-9])					
Vx,OUT	Output differential crosspoint	0.68	0.75	0.9	V	
Voн	Output High Voltage	1			V	
VOL	Output Low Voltage			0.4	V	
Supply cu	ırrent					
lcc	Maximum Quiescent Supply Current without output termination current		100	TBD	mA	V <sub>CC</sub> pin (core)
lcco <sup>f</sup>	Maximum Quiescent Supply Current, outputs terminated 50Ω to V <sub>TT</sub>		TBD	TBD	mA	VCCO pins (outputs)

a. DC characteristics are design targets and pending characterization.

<sup>b. V<sub>DIF</sub> (DC) is the minimum differential HSTL input voltage swing required for device functionality.
c. V<sub>X</sub> (DC) is the crosspoint of the differential HSTL input signal. Functional operation is obtained when the crosspoint is within the V<sub>X</sub> (DC)</sup> range and the input swing lies within the VPP (DC) specification.

d. VPP (DC) is the minimum differential input voltage swing required to maintain device functionality.

e. V<sub>CMR</sub> (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V<sub>CMR</sub> (DC) range and the input swing lies within the V<sub>PP</sub> (DC) specification.

f. ICC includes current through the output resistors (all outputs terminated to VTT).

Table 6. AC Characteristics ( $V_{CC} = 3.3V \pm 5\%$ ,  $V_{CCO} = 1.5V \pm 0.1V$  or  $V_{CCO} = 1.8V \pm 0.1V$ ,  $V_{CCO} = 1.8V \pm$ 

Symbol	Characteristics	Min	Тур	Max	Unit	Condition	
Clock input pair CLK0, CLK0 (HSTL differential signals)							
V <sub>DIF</sub>	Differential input voltage <sup>C</sup> (peak-to-peak)	0.4			V		
VX, IN	Differential cross point voltaged	0.68		0.9	V		
fCLK	Input Frequency		0-400	TBD	MHz		
tPD	Propagation Delay CLK0 to Q[0-9]			TBD	ps		
Clock inp	ut pair CLK1, CLK1 (PECL differential signals)						
VPP	Differential input voltage <sup>e</sup> (peak-to-peak)	0.2		1.0	V		
VCMR	Differential input crosspoint voltage <sup>f</sup>	1		V <sub>C</sub> C-0.6	V		
f <sub>CLK</sub>	Input Frequency		0-400		MHz	Differential	
tpD Propagation Delay CLK1 to Q[0-9]				TBD	ps	Differential	
HSTL clo	ck outputs (Q[0-9], Q[0-9])						
Vx,OUT	Output differential crosspoint	0.68	0.75	0.9	V		
Vон	Output High Voltage	1			V		
VOL	Output Low Voltage			0.5	V		
VO(P-P)	Differential output voltage (peak-to-peak)	0.5			V		
tsk(O)	Output-to-output skew			50	ps	Differential	
t <sub>sk(PP)</sub>	Output-to-output skew (part-to-part)			TBD	ps	Differential	
tJIT(CC)	Output cycle-to-cycle jitter			TBD			
DCO	Output duty cycle	TBD	50	TBD	%	DC <sub>fref</sub> = 50%	
t <sub>r</sub> , t <sub>f</sub>	Output Rise/Fall Time	0.05		TBD	ns	20% to 80%	
t <sub>PDL</sub> g	Output disable time	2.5·T + tpD		3.5·T + tpD	ns	T=CLK period	
t <sub>PLD</sub> h	Output enable time	3·T + t <sub>PD</sub>		4·T + t <sub>PD</sub>	ns	T=CLK period	

- a. AC characteristics are design targets and pending characterization.
- b. AC characteristics apply for parallel output termination of  $50\Omega$  to  $V_{TT}$ .
- c. V<sub>DIF</sub> (DC) is the minimum differential HSTL input voltage swing required for device functionality.
- d.  $V_X$  (DC) is the crosspoint of the differential HSTL input signal. Functional operation is obtained when the crosspoint is within the  $V_X$  (DC) range and the input swing lies within the  $V_{DIF}$  (DC) specification.
- e. Vpp (AC) is the minimum differential PECL input voltage swing required to maintain AC characteristics including tpd and device-to-device skew.
- f. V<sub>CMR</sub> (AC) is the crosspoint of the differential HSTL input signal. Normal AC operation is obtained when the crosspoint is within the V<sub>CMR</sub> (AC) range and the input swing lies within the V<sub>PP</sub> (AC) specification. Violation of V<sub>CMR</sub> (AC) or V<sub>PP</sub> (AC) impacts the device propagation delay, device and part-to-part skew.
- g. Propagation delay OE deassertion to differential output disabled (differential low: true output low, complementary output high).
- h. Propagation delay OE assertion to output enabled (active).

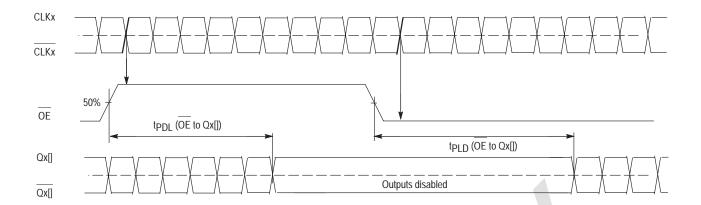


Figure 1. MC100ES8111 AC test reference

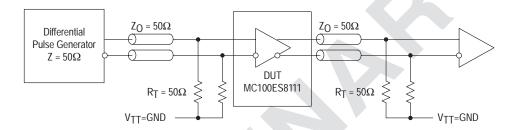


Figure 2. MC100ES8111 AC test reference

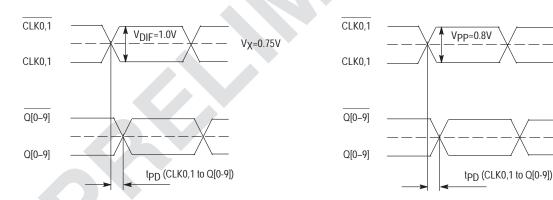
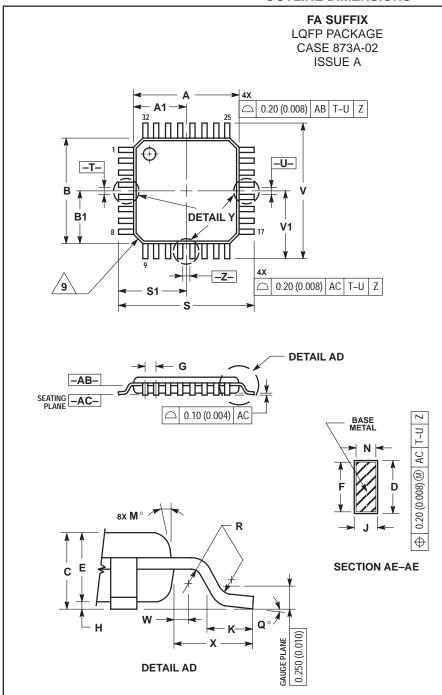


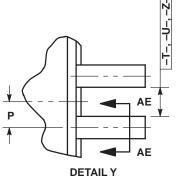
Figure 3. MC100ES8111 AC reference measurement waveform (HSTL input)

Figure 4. MC100ES8111 AC reference measurement waveform (PECL input)

V<sub>CMR</sub>=VCC-1.3V

#### **OUTLINE DIMENSIONS**





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD

- 3. DAI IUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

  4. DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.

  5. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.

  6. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.

  7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).

  8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).

  9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

	MILLIN	METERS	INCHES		
DIM	MIN MAX		MIN	MAX	
Α	7.000	BSC	0.276	BSC	
A1	3.500	BSC	0.138	BSC	
В	7.000	BSC	0.276	BSC	
B1	3.500	BSC	0.138	BSC	
С	1.400	1.600	0.055	0.063	
D	0.300	0.450	0.012	0.018	
E	1.350	1.450	0.053	0.057	
F	0.300	0.400	0.012	0.016	
G	0.800	BSC	0.031	IBSC	
Н	0.050	0.150	0.002	0.006	
J	0.090	0.200	0.004	0.008	
K	0.500	0.700	0.020	0.028	
M	12°	REF	12° REF		
N	0.090	0.160	0.004	0.006	
Р	0.400	BSC	0.016 BSC		
Q	1°	5°	1°	5°	
R	0.150	0.250	0.006	0.010	
S	9.000	BSC	0.354 BSC		
S1	4.500	BSC	0.177 BSC		
V	9.000 BSC		0.354 BSC		
V1	4.500 BSC 0.			7 BSC	
W	0.200	REF	0.008	3 REF	
Х	1.000	REF	0.039 REF		

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Motorola data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer. MOTOROLA and the logo are registered in the US Patent & Trademark Office. All other product or service names are the property of their respective owners.

© Motorola, Inc. 2002.

#### How to reach us:

USA/EUROPE/Locations Not Listed: Motorola Literature Distribution; P.O. Box 5405, Denver, Colorado 80217. 1-303-675-2140 or 1-800-441-2447

JAPAN: Motorola Japan Ltd.; SPS, Technical Information Center, 3-20-1, Minami-Azabu. Minato-ku, Tokyo 106-8573 Japan. 81-3-3440-3569

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Centre, 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong. 852–26668334

Technical Information Center: 1-800-521-6274

HOME PAGE: http://www.motorola.com/semiconductors/



MC100ES8111/D